

Product Change Notification - KSRA-25BPKT420

Date:

15 Apr 2019

Product Category:

32-bit Microcontrollers

Affected CPNs:

1

Notification subject:

CCB 3467 Final Notice: Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Notification text:

PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Pre Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with single ring plating on paddle palladium coated copper (CuPd) Bond wire

Post Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with double ring plating on paddle using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

| | Pre Change | Post Change |
|---------------------|----------------|----------------|
| Assembly Site | ASE Inc. (ASE) | ASE Inc. (ASE) |
| Wire material | CuPd | CuPdAu |
| Die attach material | CRM-1076WA | CRM-1076WA |
| Molding compound | EME-G631H | EME-G631H |
| material | EME-605111 | EME-003111 |
| Lead frame material | C7025 | C7025 |
| Lead frame Surface | Ring | Double Ring |

Note: See attached lead frame comparison

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance and qualify a new lead frame with double ring plating on paddle.

Change Implementation Status:

In Progress

Estimated First Ship Date:



May 15, 2019 (date code: 1920)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | July 2018 | | | > | April 2019 | | | May 2019 | | | | | | | |
|---------------------|-----------|----|----|----|------------|---|----|----------|----|----|----|----|----|----|----|
| Workweek | 27 | 28 | 29 | 30 | 31 | / | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 |
| Initial PCN Issue | | | | Х | | | | | | | | | | | |
| Date | | | | ^ | | | | | | | | | | | |
| Qual Report | | | | | | | | | V | | | | | | |
| Availability | | | | | | | | | ~ | | | | | | |
| Final PCN Issue | | | | | | | | | V | | | | | | |
| Date | | | | | | | | | ^ | | | | | | |
| Estimated | | | | | | | | | | | | | Х | | |
| Implementation Date | | | | | | | | | | | | | ~ | | |

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

July 27, 2018: Issued initial notification.

April 15, 2019: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on May 15, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-25BPKT420_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section. If you wish to <u>change your PCN profile</u>, including opt out, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. KSRA-25BPKT420 - CCB 3467 Final Notice: Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Affected Catalog Part Numbers (CPN)

ATSAM4LC2AA-AU ATSAM4LC2AA-AU ATSAM4LC4AA-AU ATSAM4LC4AA-AU ATSAM4LS2AA-AU ATSAM4LS2AA-AU ATSAM4LS4AA-AU